

Surge Arrester

Material Data Sheet

Product Clas	G30-A* B88069	X* (Tin plated)						
Date	4/24/2024							
IMDS ID if available								
Version	5.01							
Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)	
Active part	Ceramic	3B	Al203	100	1344-28-1	35		
	Metal	1C11	Cu	100	7440-50-8	59		
Brazing ring	Metal	4D	Ag Cu	72 28	7440-22-4 7440-50-8	4		
Plating	Plating	1C8	Sn	100	7440-31-5	2		
	'	'	'	'	Sum of total	100		
sizes [mm] Ø2.8 X 2.8	weight range[g] part name 0.2 G30-A90XSMD G30-A200XSMD G30-A500XSMD				material numbers B88069X4103* B88069X6403* B88069X2243*			
Not part of a Produ	ict Class				_			
Contact	Mohd Faizal Jamaludin			Important rema	Important remarks:			
Division	TDK ELECTRONICS (MALAYSIA) SDN BHD			,	, , , , , , , , , , , , , , , , , , , ,			
Address		rau Ind IV, 81100 JB Ma	•	product parts, su regulated.	product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.			
	Tel: +60-7-3566629	mailto: mohdfaizal.jama	lludin@tdk.com	2) This Mate	· ·			
, ,	rable or prohibited substar centage of substance	ices acc. GADSL)		present knowled specifications, ur AFFILIATES HE WHETHER EXP AND VALUES C REPRESENTAT				
					uirements according to Art. 4 (so electrical and electronic equipments)		ective 2011/65/EU of	
	Lead as an alloying elemen Copper alloy containing up Lead in high melting tempe Electrical and electronic con : Lead in dielectric ceramic in I: Lead in dielectric ceramic in	t in steel for machining pur t in aluminium containing u to 4 % lead by weight; rature type solder (i.e. lead mponents containing lead in a capacitors for a rated volt a viable electrical connect	poses and in galvanized steel p to 0,4 % lead by weight; -based alloys containing 85 % n a glass or ceramic other than age of 125 V AC or 250 V DC age of less than 125 V AC or 2	containing up to 0,35 % lead by by weight or more lead); n dielectric ceramic in capacitors or higher;	, e.g. piezoelectronic devices, or in a	glass or ceramic matrix compo	bund;	